



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

the application of

SALDANA et al.

Application No. 09/748,708

Filed: December 22, 2000

For: POLISHING APPARATUS AND METHODS
HAVING HIGH PROCESSING WORKLOAD
FOR CONTROLLING POLISHING PRESSURE
APPLIED BY POLISHING HEAD

Atty. Docket No. LAM2P222A

Examiner: Unassigned

Group Art Unit: 3723

Date: May 2, 2001

TECHNOLOGY CENTER 3700

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on May 2, 2001.

Signed: _____

Meely J. Weldy
Meely J. Weldy

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

IN THE SPECIFICATION

Please replace the paragraph that begins on page 1, line 9 with the following:

A1 --This Application claims 35 U.S.C. § 120 priority based on, and is a continuation-in-part (CIP) of: (1) co-pending U.S. Patent Application No. 09/644,135, filed August 22, 2000, entitled "SUBAPERTURE CHEMICAL MECHANICAL POLISHING SYSTEM," by Miguel A. Saldana, John M. Boyd, Yehiel Gotkis, and Aleksander A. Owczarz (the First Parent Application); and (2) co-pending U.S. Patent Application No. 09/668,667, filed September 22, 2000, entitled "APPARATUS AND METHODS FOR CONTROLLING RETAINING RING AND WAFER HEAD TILT FOR CHEMICAL MECHANICAL POLISHING," by Damon Vincent Williams (the Second Parent Application), each U.S. Patent Application is hereby incorporated by reference. Additionally, this Application is also related to co-pending U.S. Patent Application No.

09748708-050701